

NOTES:

1. THE FOLLOWING ABIDES BY THE DSC INSPECTION DOCUMENTATION: # 27-00200-000.
2. PART MUST WITHSTAND, WITH NO BLISTERING, DELAMINATION, SOLDERMASK FLAKING OR ANY OTHER DAMAGE 3 REFLOW PASSES WITH MAXIMUM TEMPERATURE OF 260± 5° C AND 45 TO 90 SECONDS ABOVE 200° C FOLLOWED BY AQUEOUS OR SEMI-AQUEOUS CLEANING.

3. A) MINIMUM DESIGNED CONDUCTOR WIDTH IS 0.005.
- B) MINIMUM DESIGNED CONDUCTOR SPACE IS 0.005.

- C) MAXIMUM ALLOWABLE LINE REDUCTION DUE TO PIN HOLES, NICKS ON LINE RUNS, AND LINE SHRINKAGE TO BE 10%.
4. MINIMUM LAYER TO LAYER DIELECTRIC FINISH .003, FOR MULTILAYER BOARDS ONLY.
5. COPPER WALL THICKNESS TO MEET IPC-600 CLASS 2.
6. MINIMUM ANNULAR RING PER IPC-6012A (CURRENT REVISION) CLASS 2.
7. ALL FIDUCIAL ALIGNMENT MARKS ARE TO BE PLATED PER THE PROCESS BELOW. MAXIMUM 10% SIZE REDUCTION ALLOWED. .250 SOLDERMASK CLEARANCE AROUND FIDUCIALS.
8. SOLDERMASK : MASK HEIGHT MUST NOT EXCEED .0014 INCHES.
9. SOLDERMASK REGISTRATION TO BE ± .003.
10. SIDE TO SIDE REGISTRATION TO BE ± .003.
11. REMOVE ALL BURRS AND SHARP EDGES IN ORDER TO MEET DIMENSIONAL TOLERANCES.
12. THE FOLLOWING MUST BE PRESENT & LOCATED PER PAGE 2. (ETCHED, SOLDERMASK, SILKSCREENED OR STAMPED WITH NON-CONDUCTIVE INK).
- A) "PART NUMBER"
- B) "REVISION LETTER"
- C) "SIDE A" FOR SIDE A, "SIDE B" FOR SIDE B.
- D) DATE CODE
- E) MANUFACTURER'S UL LOGO
13. EXTERNAL COPPER WEIGHT WILL NOT EXCEED 1.5 OZ.
14. MAXIMUM ALLOWABLE WARP PER IPC-600.
15. SOLDERMASK ARTWORK MUST NOT BE EDITED IN ANY WAY. THE ARTWORK MANDATES A MINIMUM CLEARANCE AROUND BOARD EDGE TO REDUCE PEEING AND KEEP MASK OFF EDGE CONNECTORS AND LEAD FRAME PADS IF APPLICABLE.

PROCESSES: SOLDERMASK OVER BARE COPPER (SMOBC) AND

ELECTROLESS NI IMMERSION GOLD (ENIG).
MUST MEET IPC-S-804 SOLDERABILITY.

- 1.) Au (IMMERSION 3-10 MICRO INCHES).
- 2.) Ni (ELECTROLESS 100-300 MICRO INCHES).
- 3.) SOLDERMASK PER IPC-SM-840 (CURRENT REVISION), USING ARTWORK NO. 1 FOR SIDE A AND NO. 4 FOR SIDE B.

PROCESSES: ELECTROLYTIC Ni GOLD

MUST MEET IPC-S-804 SOLDERABILITY.

- 1.) Au (ELECTROLYTIC 10-30 MICRO INCHES).
- 2.) Ni (ELECTROLYTIC 100-500 MICRO INCHES).
- 3.) SOLDERMASK PER IPC-SM-840 (CURRENT REVISION), USING ARTWORK NO. 1 FOR SIDE A AND NO. 4 FOR SIDE B.

TABLE FOR ARTWORK

NO.	DESCRIPTION	STARTING COPPER WT.	REVISION
1	SIDE A SOLDER MASK		A
2	LAYER 1 SURFACE (SIDE A)	0.5 OZ.	A
3	LAYER 2 SURFACE (SIDE B)	0.5 OZ.	A
4	SIDE B SOLDER MASK		A

DRILL/TEST DATA

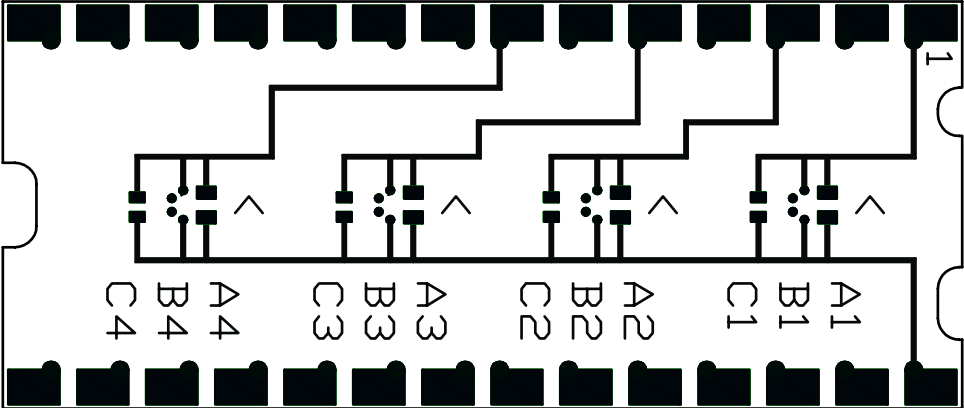
DESCRIPTION	SIDE	REVISION
HOLE CONFIGURATION	A	A
HOLE CONFIGURATION	B	
CONTINUITY TEST	A	
CONTINUITY TEST	B	
PROFILE	A	
PROFILE	B	

Σ = CRITICAL DIMENSION

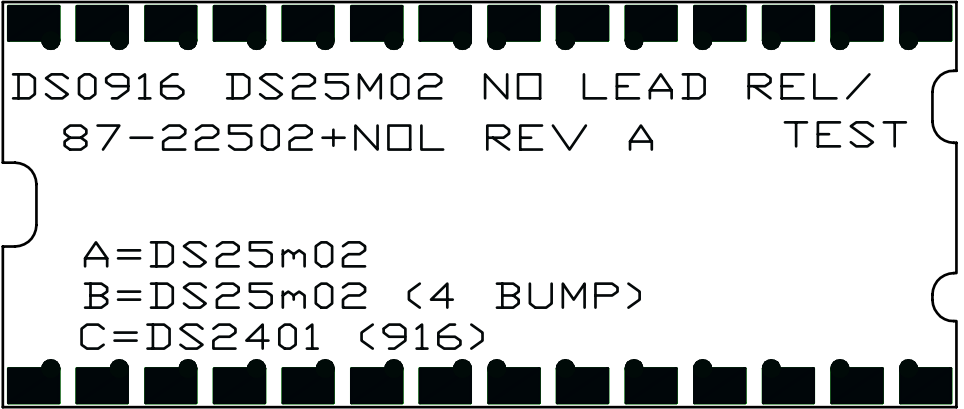
HOLE SCHEDULE

SYM	FINISHED HOLE DIAMETER	HOLE COUNT		REMARKS
	UNSUPPORTED	PLATED THRU +.007-.003	CELL PANEL	
⚠	.120 ±.003	--	0	4
○		.012	28	672
				VA HOLES

SIDE - A



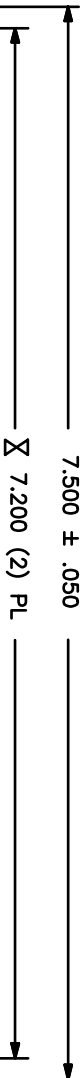
SIDE - B



DRILLS (REFERENCE ONLY NOT TO SCALE)
(SIDE A SHOWN)

.041 $\pm$.003 Σ (TOTAL OVERALL THICKNESS)
(OVER PLATING)

(SIDE VIEW)



SEE DETAIL-A

SEE DETAIL-B

0.120 $\pm$.003 DIA.
(4 PLCS)

FIDUCIAL ALIGNMENT MARK
(0.100 DIAMOND TIP TO TIP)
(4 PLCS SEE NOTE 7)

SEE NOTE 12D

SEE NOTE 12E

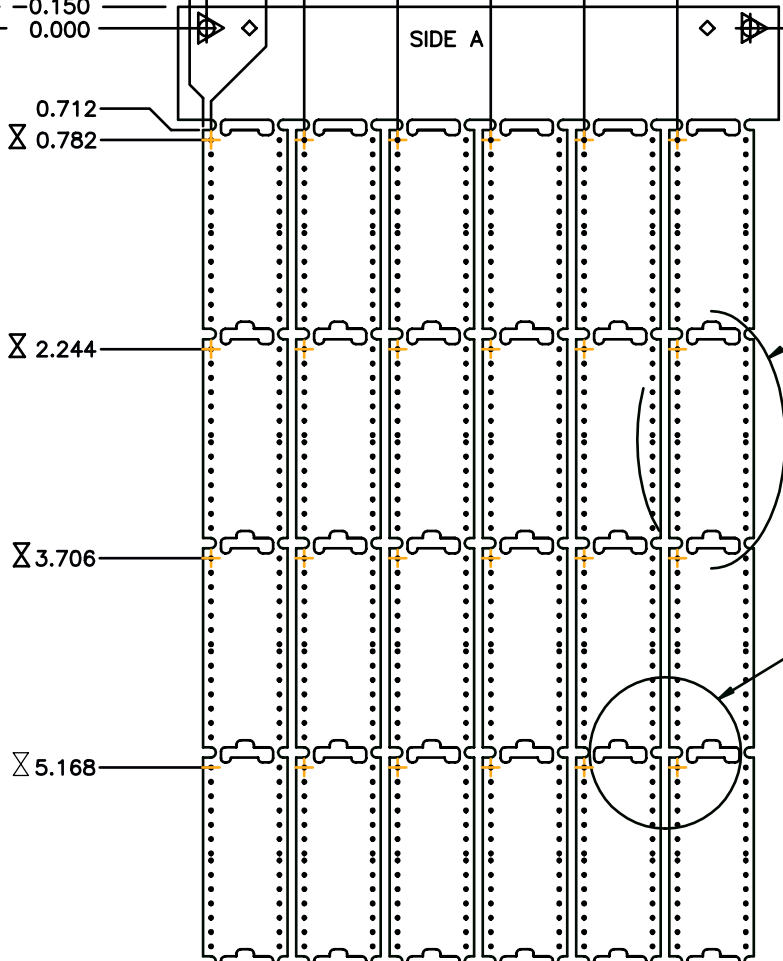
4.200 $\pm$.050

Σ 3.800 (2) PL

.300
(4 PLCS)

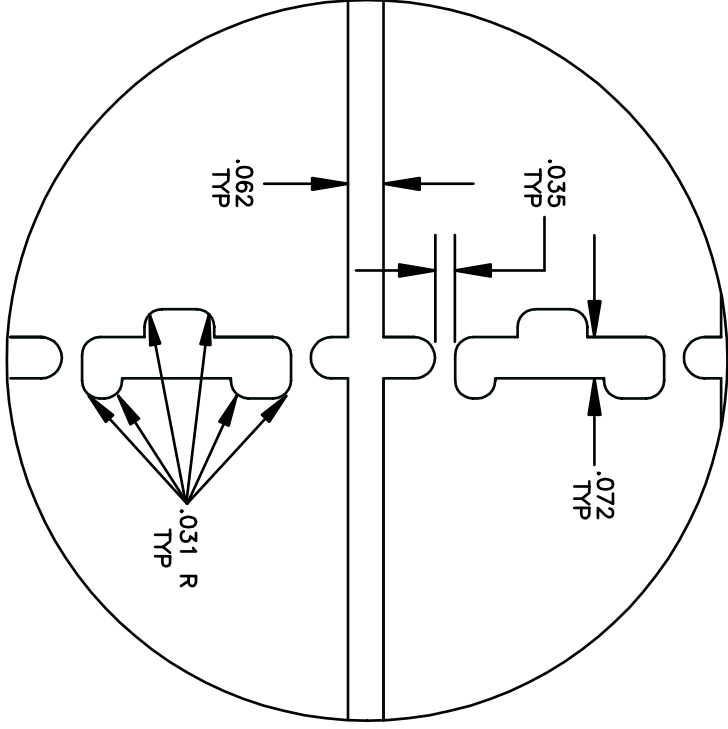
0.000

87-22502+NOL
REV A

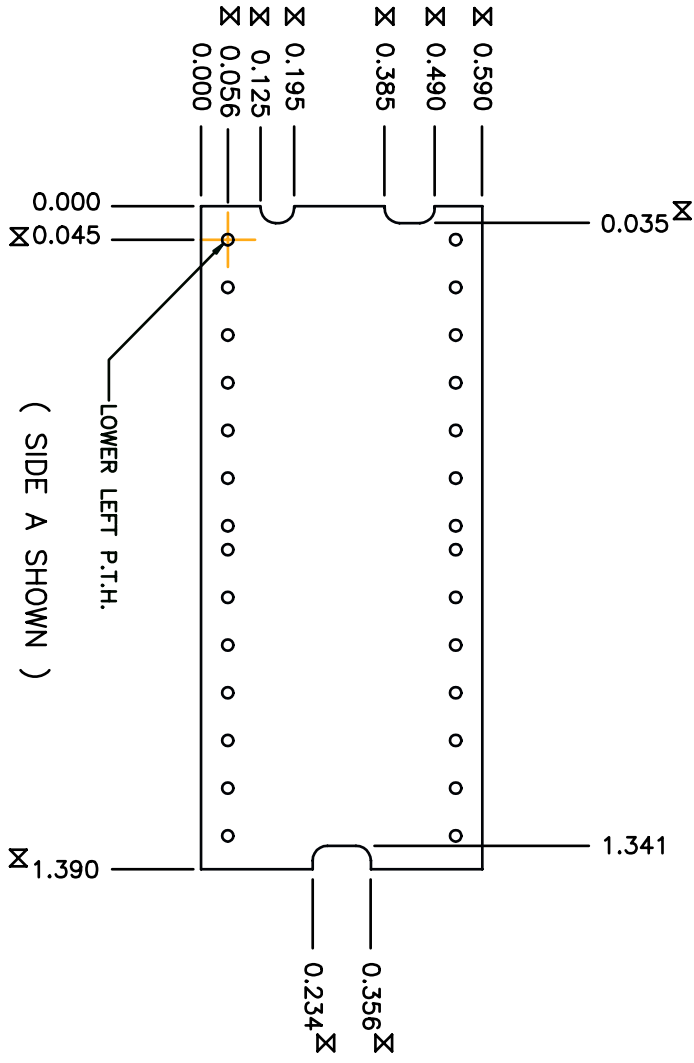


(SIDE -A- SHOWN)

SCALE = 1.5 : 1



DETAIL-B
SCALE = 6:1



(SIDE A SHOWN)

DETAIL-A
SCALE = 5:1